

Section 25

Bipolar Junction Transistor – Design

25.4 Emitter Doping Design

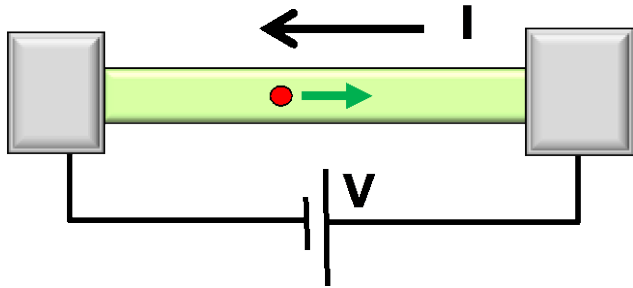
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School of Electrical and
Computer Engineering

Section 25

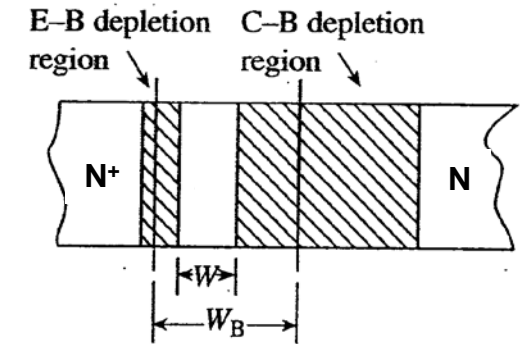
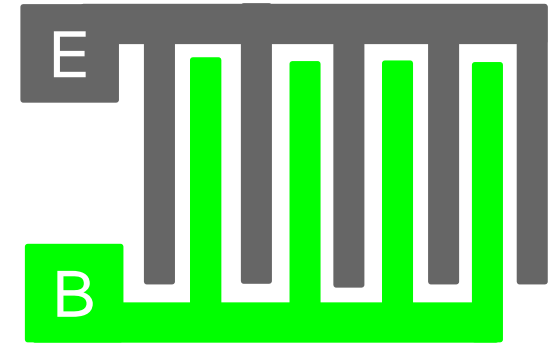
Bipolar Junction Transistor - Design



$$I = G \times V$$

$$= q \times n \times v \times A$$

↑ charge density ↑ velocity area

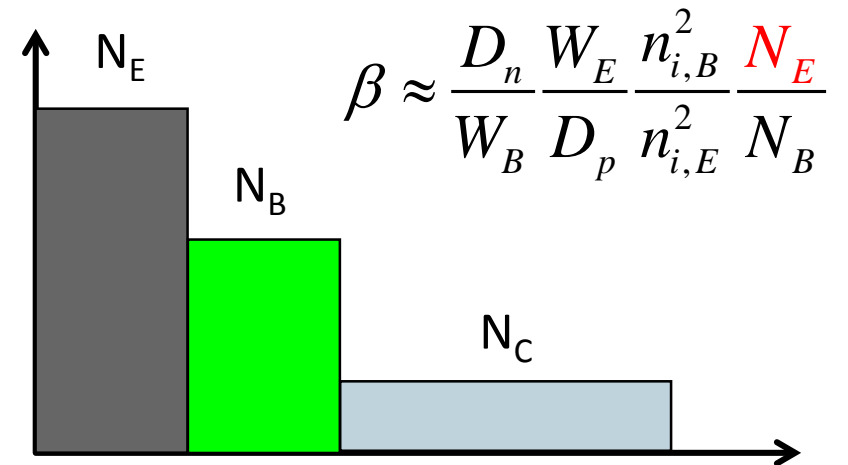


$$x_{p, BE} = \sqrt{\frac{2k_s \epsilon_0}{q} \frac{N_E}{N_B (N_E + N_B)} (V_{bi} - V_{BE})}$$

$$x_{p, BC} = \sqrt{\frac{2k_s \epsilon_0}{q} \frac{N_C}{N_B (N_C + N_B)} (V_{bi} - V_{BC})}$$

- > • 25.1 Current gain in BJTs
- > • 25.2 Base Doping Design
 - » Current Crowding – Non-Uniform Turn-On
 - » Punch-through
 - » Base Width Modulation
- > • 25.3 Collector Doping Design (Kirk Effect, Base Pushout)
- > • 25.4 Emitter Doping Design ← status
- > • 25.5
- > • 25.6

$$V_A = -\frac{qN_B W_B}{C_{CB}} \quad C_{CB} = \frac{K_s \epsilon_0}{x_{n,C} + x_{p,B}}$$



Perhaps High Doping in Emitter?

$$\beta \approx \frac{D_n}{W_B} \frac{W_E}{D_p} \frac{n_{i,B}^2}{n_{i,E}^2} \frac{N_E}{N_B} = \frac{D_n}{W_B} \frac{W_E}{D_p} \frac{N_C N_V e^{-E_{g,B}/kT}}{N_C N_V e^{-E_{g,E}/kT}} \frac{N_E}{N_B}$$

$$\beta \approx e^{-\Delta E_g/kT} \frac{N_E}{N_B}$$

Example increase doping by 40x:
 N_E from 10^{18} cm^{-3} to $4 \times 10^{19} \text{ cm}^{-3}$

ΔE_G from 25meV to 150meV

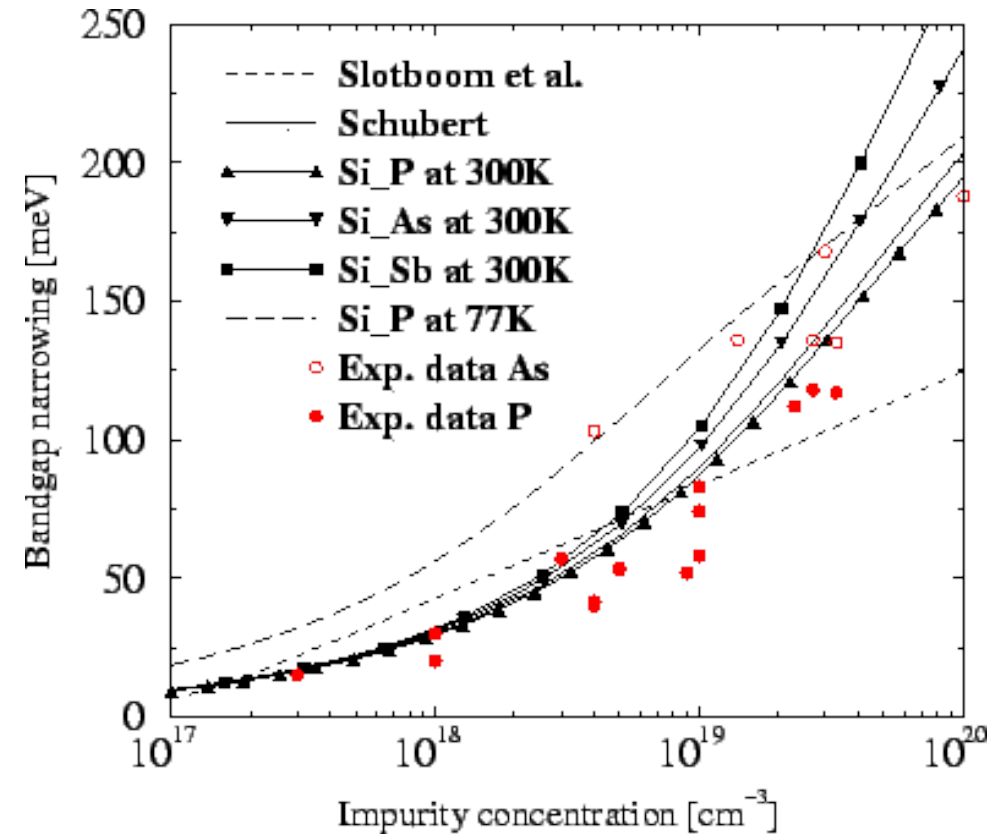
$$\Delta E_{G,net} = 125 \text{meV} \sim 5k_B T$$

$$e^{-5} \sim 6.73 \cdot 10^{-3}$$

$$\Delta \beta \sim 40 \times 6.73 \cdot 10^{-3} = 0.27$$

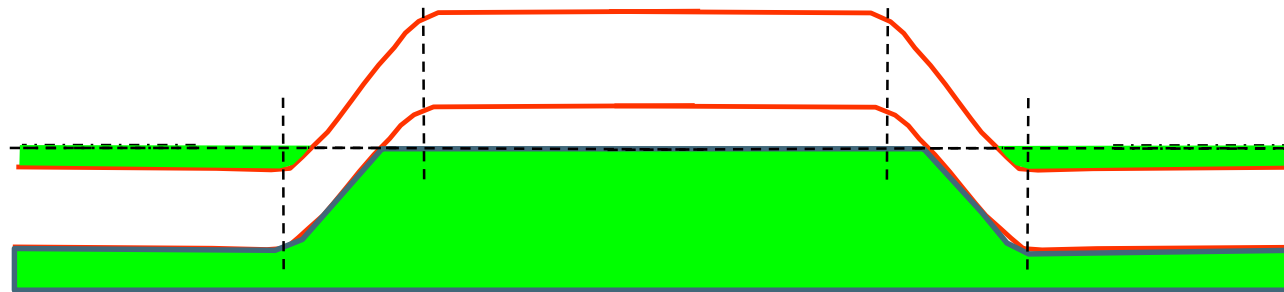
=> Reduction in gain

Very high doping can narrow the bandgap of a semiconductor!



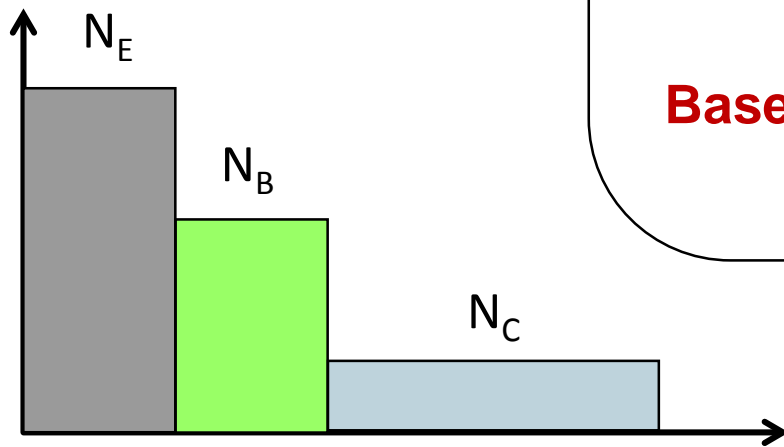
Perhaps High Doping in Emitter?

(Esaki-like) Tunneling cause loss of base control ...



Doping for Gain

$$\beta_{dc} \approx \frac{D_n}{W_B} \frac{W_E}{D_p} \frac{n_{i,B}^2}{n_{i,E}^2} \frac{N_E}{N_B}$$



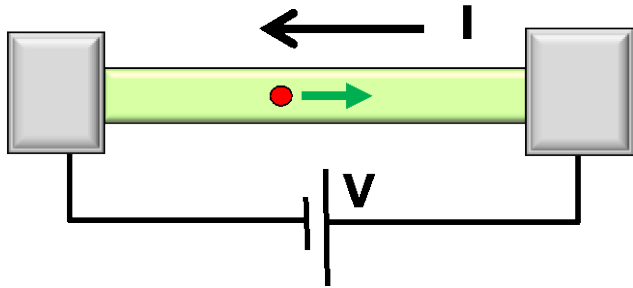
Emitter doping: As high as possible without *band gap narrowing*

Base doping: As low as possible, without *current crowding, Early effect*

Collector doping: Lower than base doping *without Kirk Effect*

Base Width: As thin as possible without *punch through*

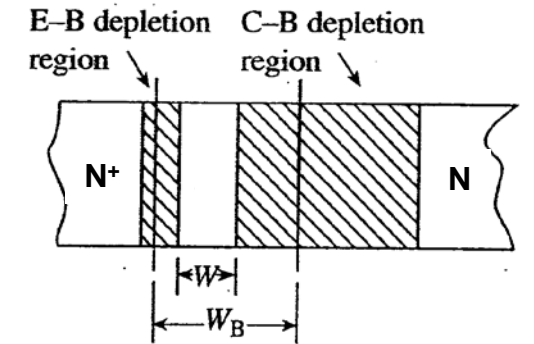
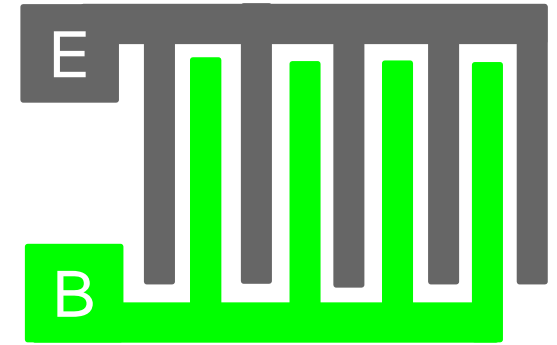
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 ↑ velocity
 ↑ area



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> • 25.4 Emitter Doping Design

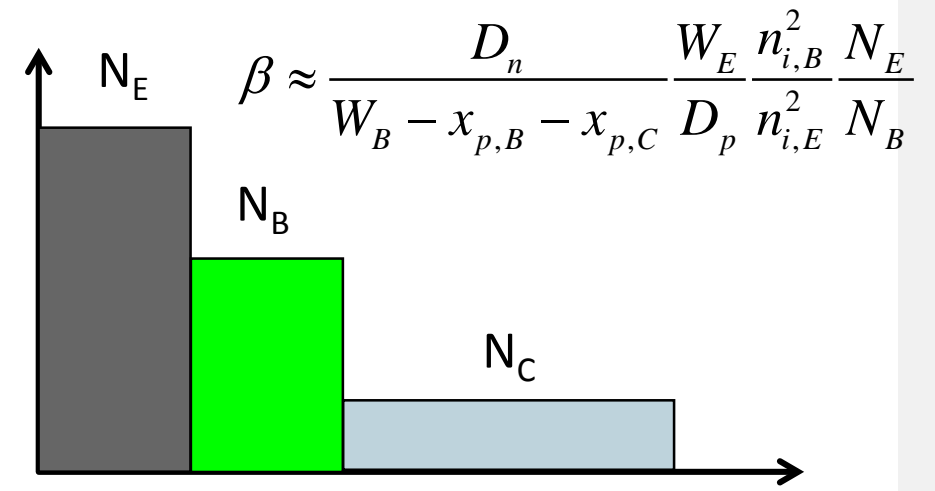


> • 25.5

> • 25.6

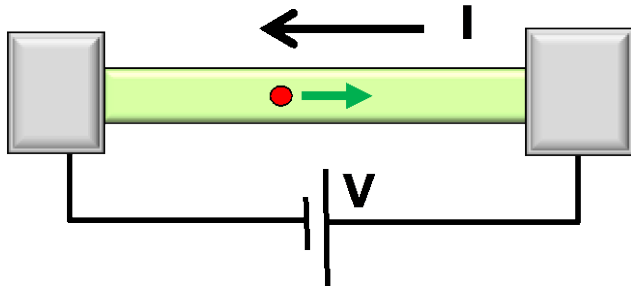
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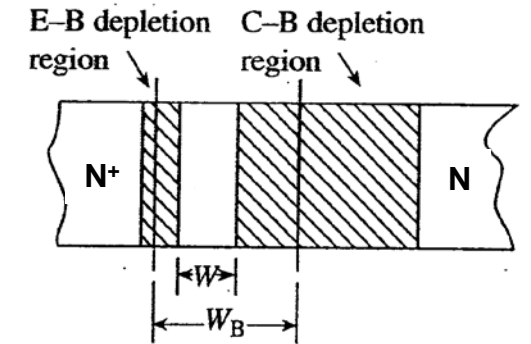
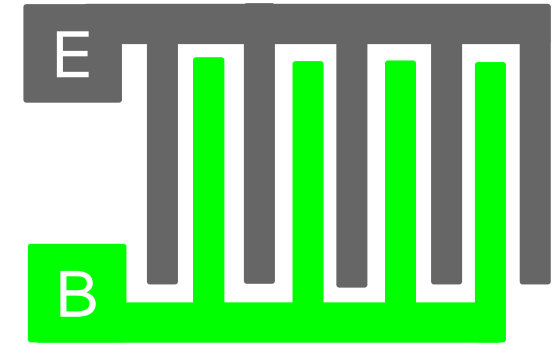
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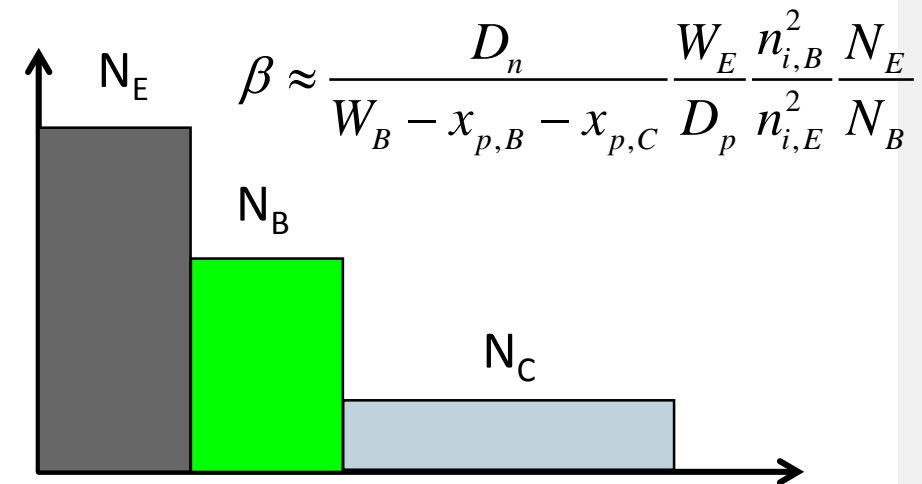
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> • 25.5 Poly-Si emitter

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